

D30FD60K

Fast Recovery Diodes

600V, 30A

Feature

- SMD
- High Voltage
- Low Noise
- Pb free terminal
- RoHS:Yes

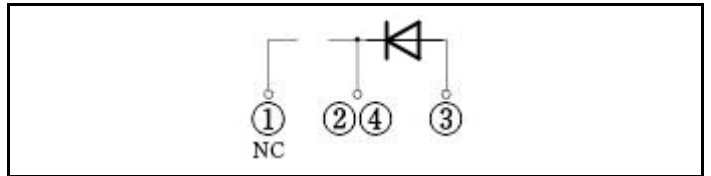
OUTLINE

Package (House Name): FD

Package (JEITA Code): SC-83 similar



Equivalent circuit



Absolute Maximum Ratings (unless otherwise specified : Tc=25°C)

Item	Symbol	Conditions	Ratings	Unit
Storage temperature	T _{stg}		-55 to 150	°C
Junction temperature	T _j		150	°C
Repetitive peak reverse voltage	V _{RRM}		600	V
Average forward current	I _{F(AV)}	50Hz sine wave, Resistance load, With heatsink, T _c =102°C	30	A
Surge forward current	I _{FSM}	50Hz sine wave, Non-repetitive 1 cycle, Peak value, T _j =25°C	300	A
Surge forward current	I _{FSM1}	t _p =1ms, Non-repetitive, T _j =25°C	948	A

※ :See the original Specifications

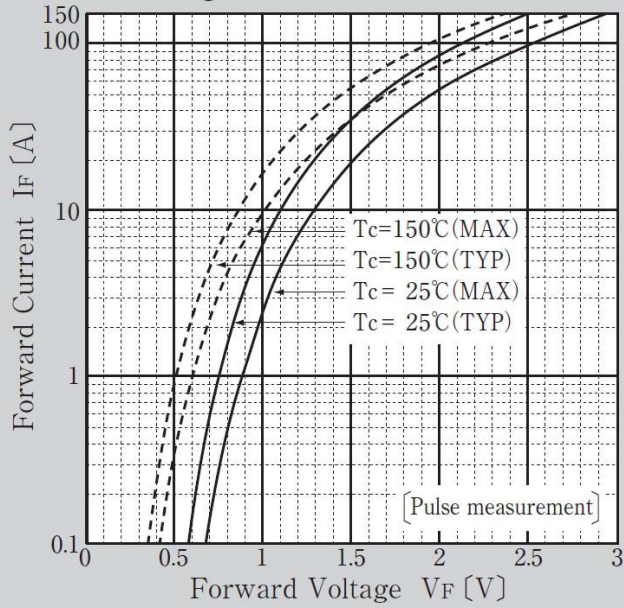
Electrical Characteristics (unless otherwise specified : Tc=25°C)

Item	Symbol	Conditions	Ratings			Unit
			MIN	TYP	MAX	
Forward voltage	V _F	I _F =30A, Pulse measurement			1.7	V
Reverse current	I _R	V _R =600V, Pulse measurement			10	μA
Reverse recovery time	t _{rr}	I _F =0.5A, I _R =1A, 0.25I _R			95	ns
Reverse recovery time	t _{rr}	I _F =1.0A, V _R =30V, di/dt=-50A/μs, 0.25I _R			72	ns
Reverse recovery time	t _{rr}	I _F =1.0A, V _R =420V, di/dt=-50A/μs, 0.25I _R			84	ns
Total capacitance	C _t	f=1MHz, V _R =10V		105		pF
Thermal resistance	R _{th(j-c)}	Junction to case, With heatsink			0.8	°C/W
Thermal resistance	R _{th(j-a)}	Junction to ambient			65	°C/W

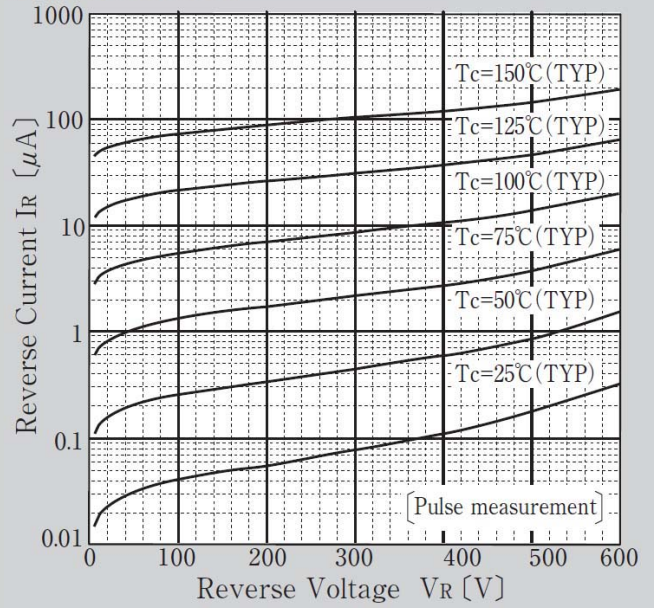
* :See the original Specifications

CHARACTERISTIC DIAGRAMS

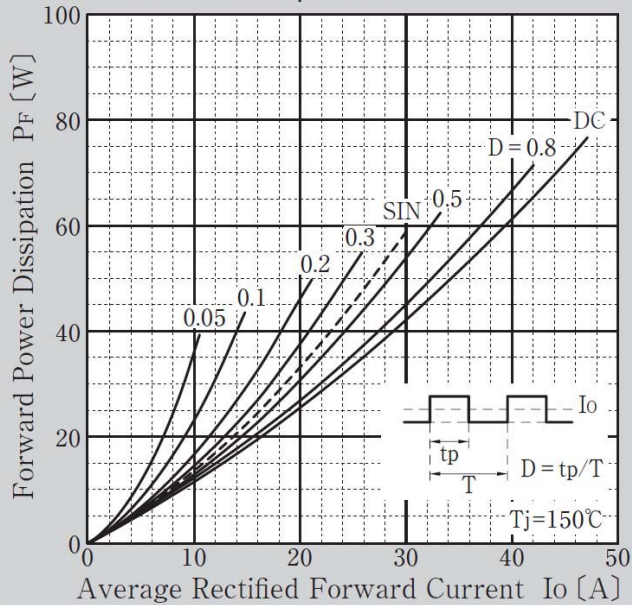
Forward Voltage



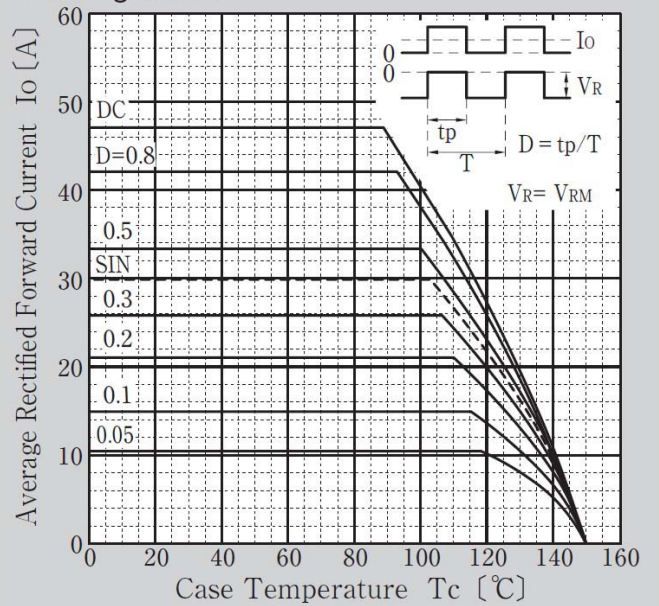
Reverse Current



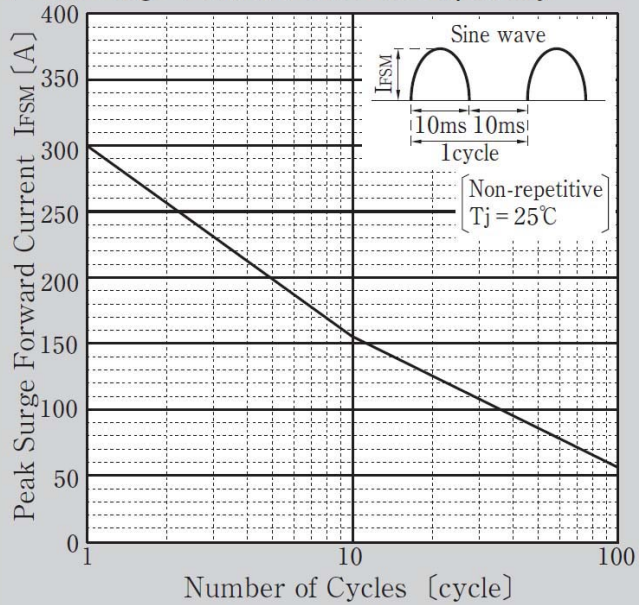
Forward Power Dissipation



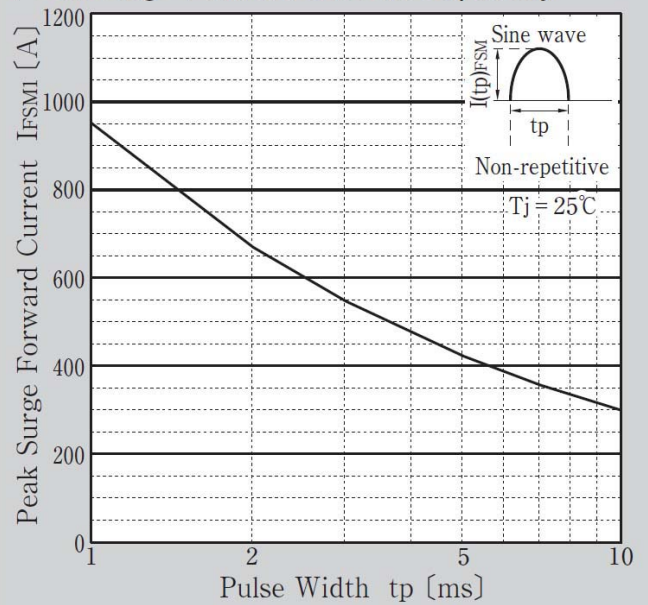
Derating Curve



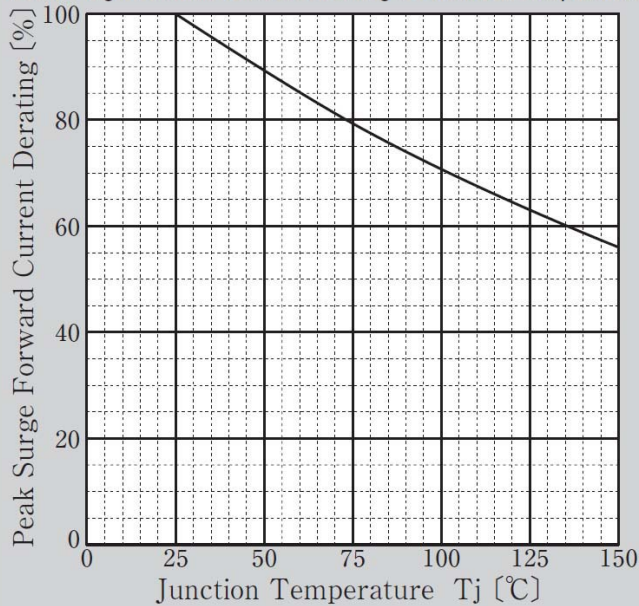
Peak Surge Forward Current Capability



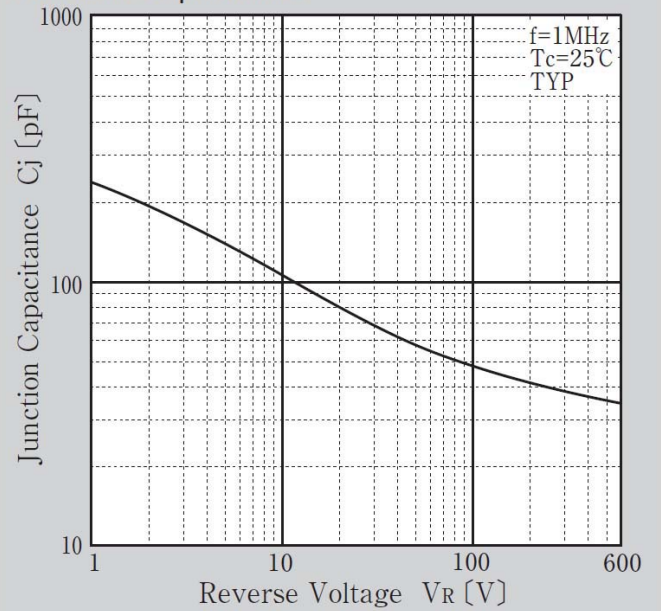
Peak Surge Forward Current Capability



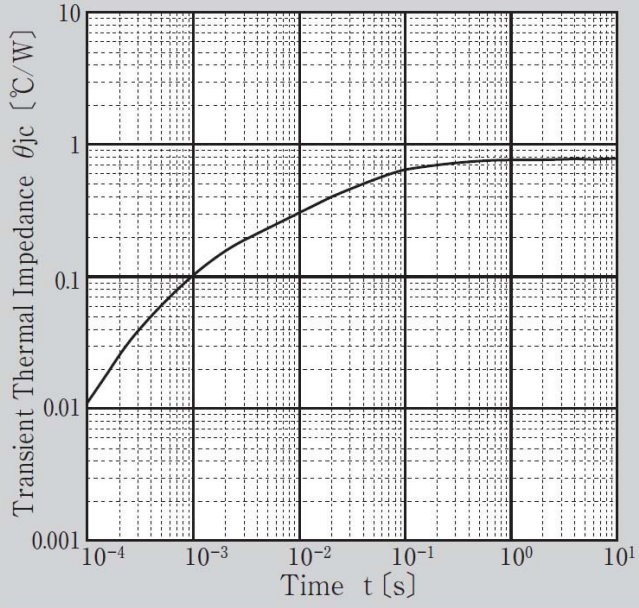
Peak Surge Forward Current Derating vs Junction Temperature



Junction Capacitance

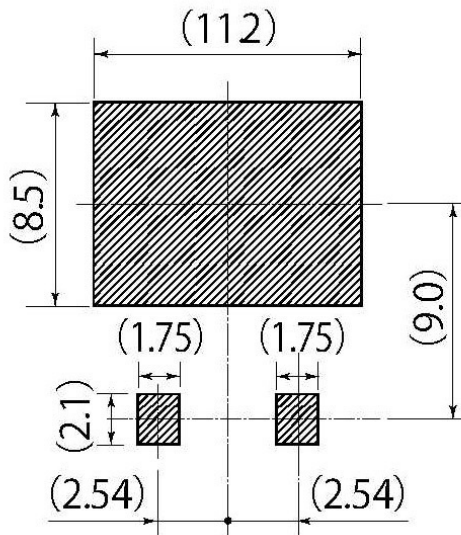
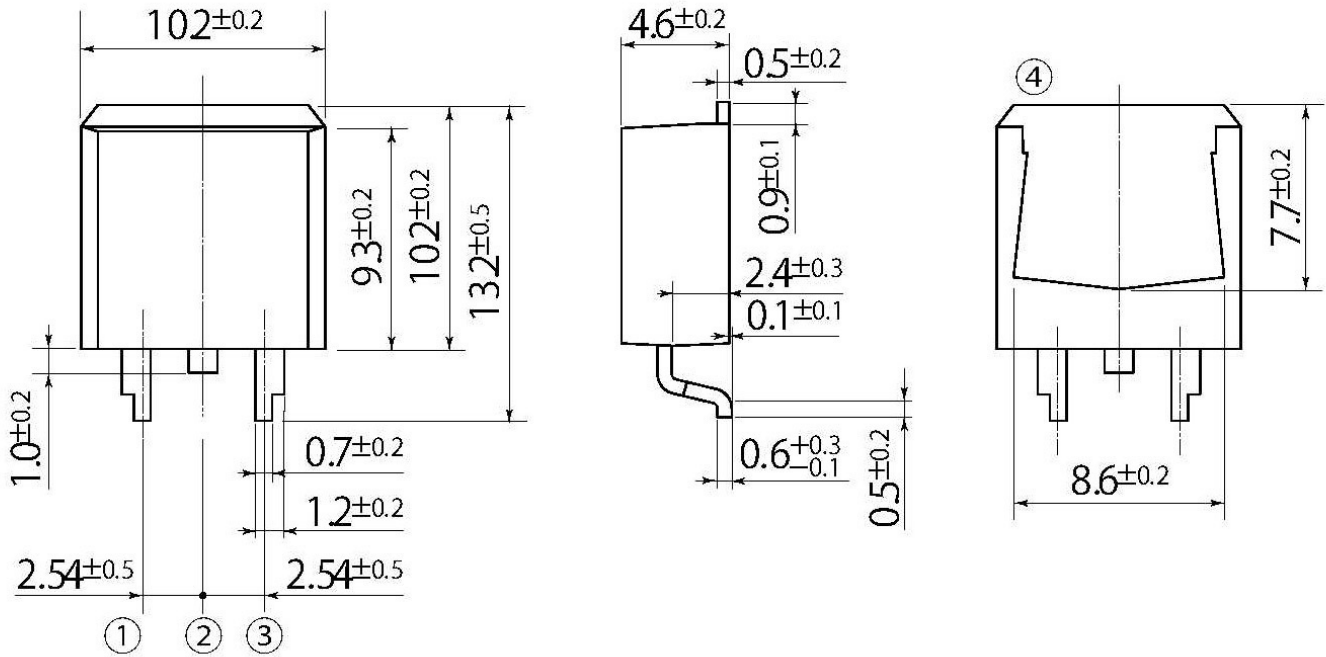


Transient Thermal Impedance



H2

JEDEC Code	—
JEITA Code	SC-83 similar
House Name	FD



Referential Soldering Pad

• Optimize soldering pad to the board design and soldering condition.

Notes

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